



ESTD - 1928



Presentation On

Artificial Intelligence In The

Semiconductor Industry

Presented by

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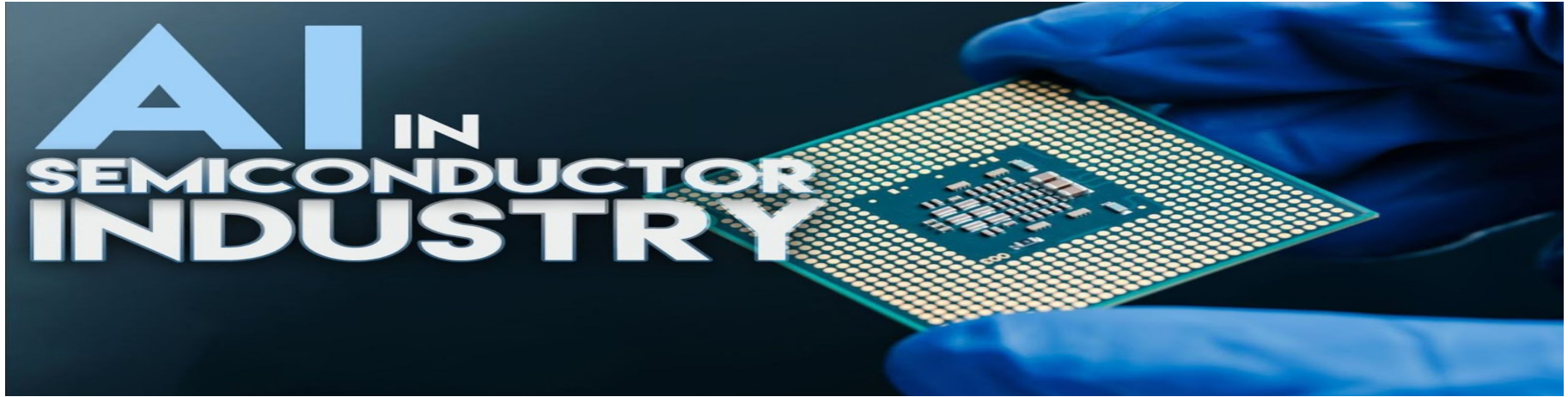
Third Year, Department of Computer engineering

Topic-AI in Semiconductor Industry

Presentation Outline

- 1. Introduction**
- 2. Artificial Intelligence Vs Human Intelligence**
- 3. Different types of AI chips**
- 4. Literature survey**
- 5. AI in Semiconductor industry application**
- 6. Future Scope**

1.Introduction



This demand is changing the semiconductor supply chain by directly impacting design & manufacturing decisions.

Demand for Specialized Sensors, IC's, Improved Memory & Enhanced Processors is increasing.

Artificial Intelligence VS Human Brain

1.AI Chips —> Brain of human being

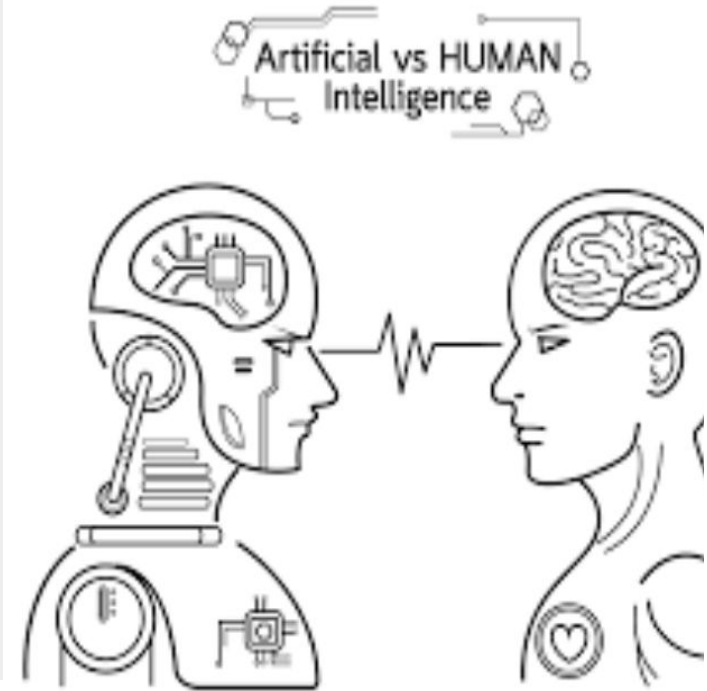
2.AI Chips is the hardware on which the AI Software and applications Run.

3AI Cips like CPU, GPU, FPGA & ASIC are developed by companies like Intel, AMD, NVIDIA etc

4.CPU: Intel, AMD

5.GPU: NVIDIA, Intel, AMD

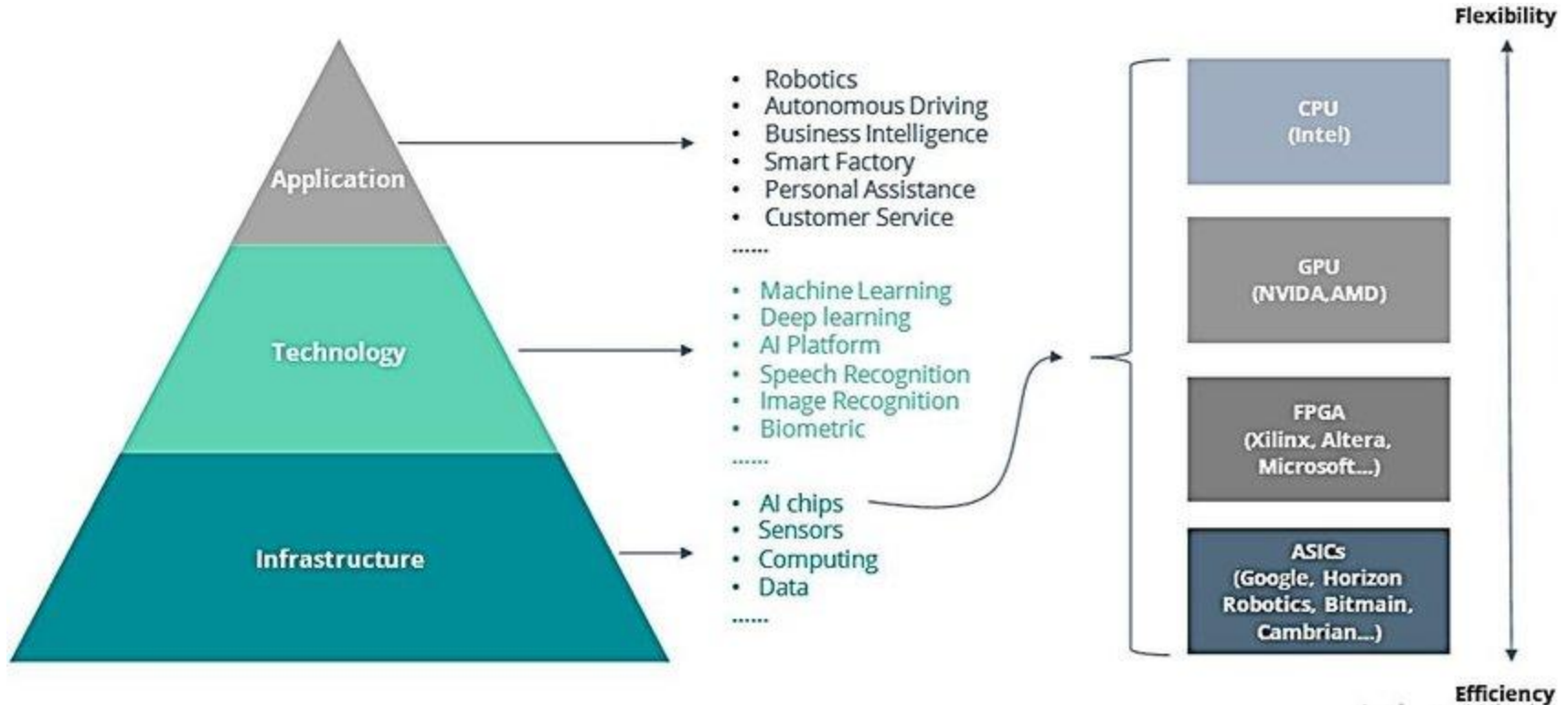
6.FPGA: Xilinx, Intel (formerly Altera)



Artificial Intelligence VS Human Brain



Framework of Artificial Intelligence



Layers of Artificial Intelligence

A. The Infrastructure Layer

This layer consists of the AI Chips and sensors required to support the technology layer's decision-making, reasoning, and learning abilities.

B. The Technology Layer

This layer employs various technologies such as deep learning, machine learning and speech and image recognition and hence is responsible for driving this layer and is fundamental in AI algorithms processing.

C. The Application Layer

This layer offers different domains where AI Chips can be utilized such as business intelligence, automotive industry, customer services, and individual assistance

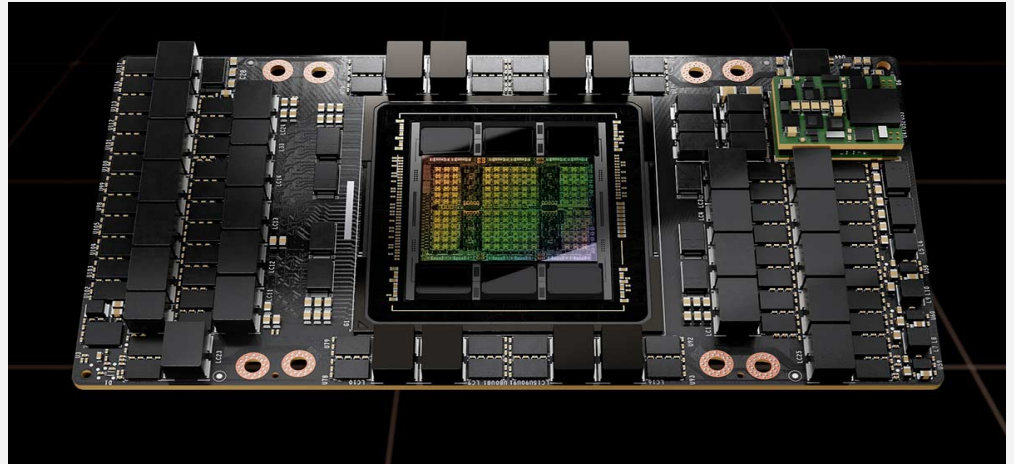
Different types of AI Chips

1.Graphics Processing Unit

A GPU AI chip, also known as a **Graphics Processing Unit** Artificial Intelligence chip, is a specialized hardware component designed to **accelerate** artificial intelligence (AI) and machine learning (ML) workloads.

Characteristics & Advantages

1. Deep Learning
- 2.AI Accelerations
- 3.Specialized AI Hardware



Different types of AI Chips

2.Field Programmable Gate Array

An FPGA : **Field-Programmable Gate Array** consist of an **array** of **logic gates** and **programmable interconnects** that allow for the **creation** of custom digital circuits and systems.

Characteristics & advantages

- 1.Fixed in functionality
- 2.Programmability: Verilog,VHDL



XILINX FPGA

Applications of FPGA



Different types of AI Chips

3.ASIC

ASIC:**Application Specific Integrated Circuits** execute a specific AI algorithm or function with high efficiency and performance

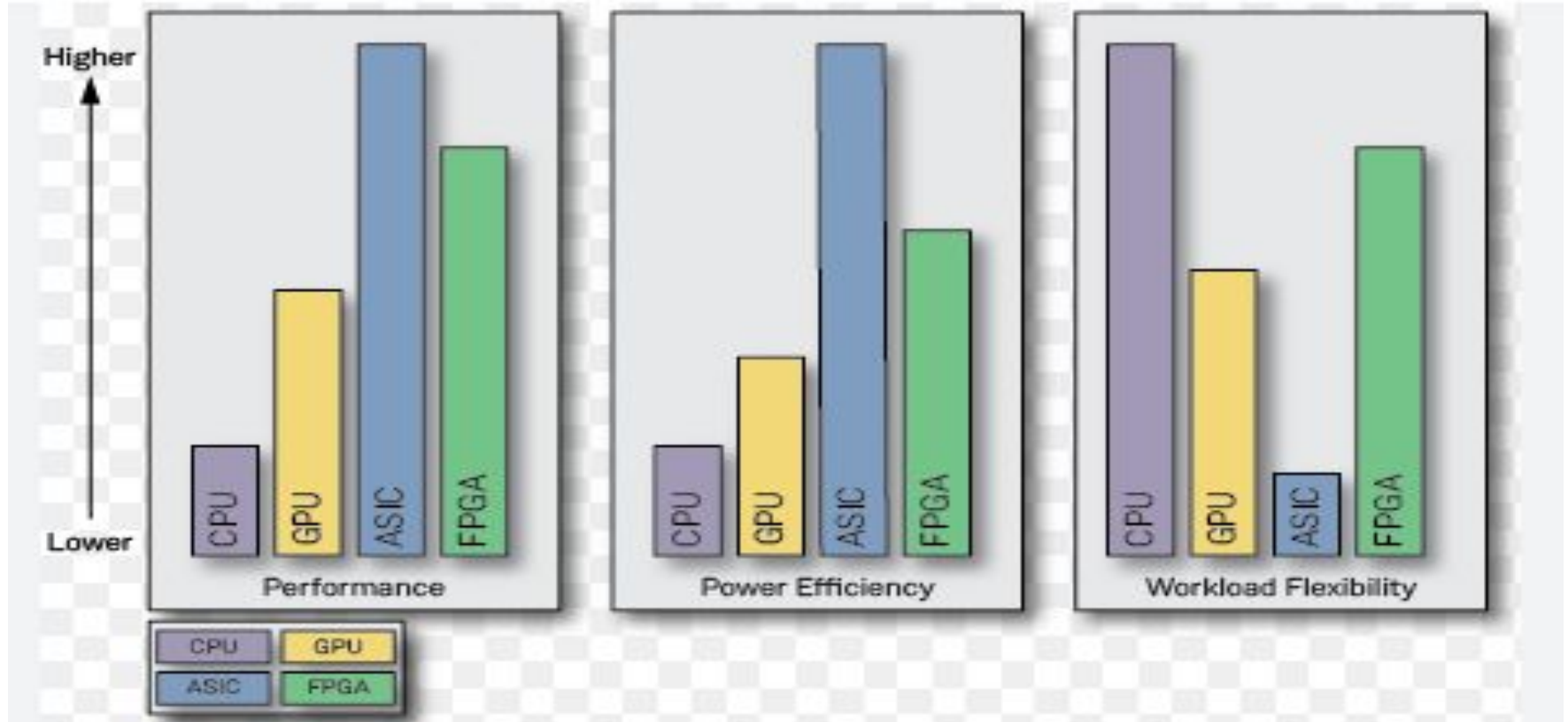
Applications

- 1.Consumer electronics:**Smartphones, Cameras
- 2.Telecommunications:**Modems
- 3.Cryptography:**security
- 4.Industrial Automations:**automate maufacturing

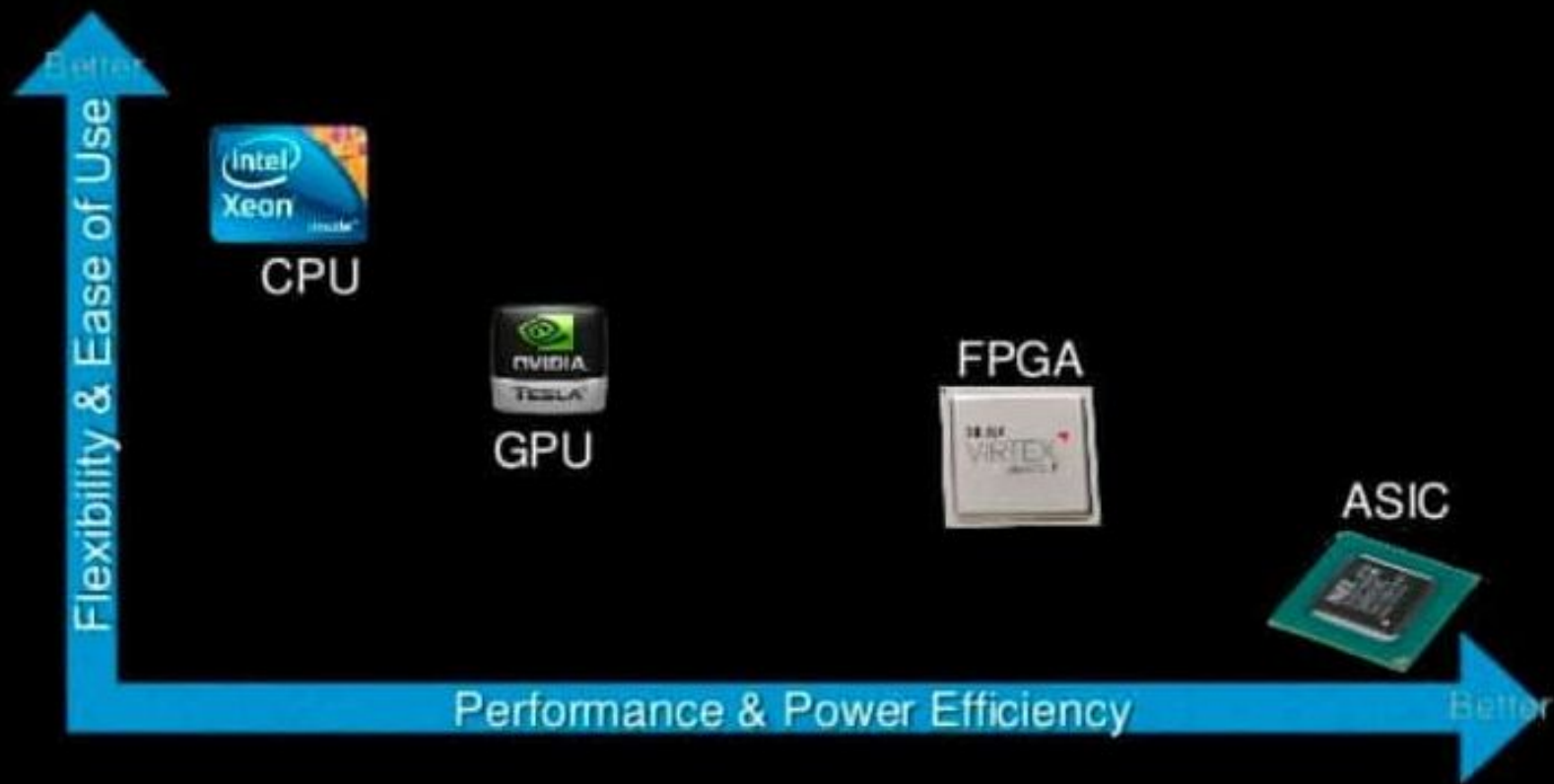


| Core Type | Custom ASIC | Typical Power Consumption | Description | Strengths | Constraints |
|-----------|-------------|---------------------------|--|---|--|
| CPU | | High | Flexible, general purpose processing units | <ul style="list-style-type: none"> • Complex instructions and tasks • System management | <ul style="list-style-type: none"> • Possible memory access bottlenecks • Few cores (4-16) |
| GPU | | High | Parallel cores for high quality graphics rendering | <ul style="list-style-type: none"> • High performance AI processing • Highly parallel core with 100's or 1,000's of cores | <ul style="list-style-type: none"> • High power consumption • Large footprint |
| FPGA | | Medium | Configurable logic gates | <ul style="list-style-type: none"> • Flexible • In-field reprogrammability | <ul style="list-style-type: none"> • High power consumption • Programming complexity |
| ASIC | | Low | Custom logic designed with libraries | <ul style="list-style-type: none"> • Fast and low power consumption • Small footprint | <ul style="list-style-type: none"> • Fixed function • Expensive custom design |


Literature Survey



New Type of Cloud Accelerator - FPGAs



FPGA Vs ASIC (CPU & GPU)

|  | FPGA | ASIC |
|---|--------|---------|
| Time to Market | Fast | Slow |
| NRE | Low | High |
| Design Flow | Simple | Complex |
| Unit Cost | High | Low |
| Performance | Medium | High |
| Power Consumption | High | Low |
| Unit Size | Medium | Low |

NRE: Development Cost

When a new product has to be launched Companies use FPGA. But once product is stable they develop an ASIC, Because ASIC per unit cost is low.

Comparison between AI Chips

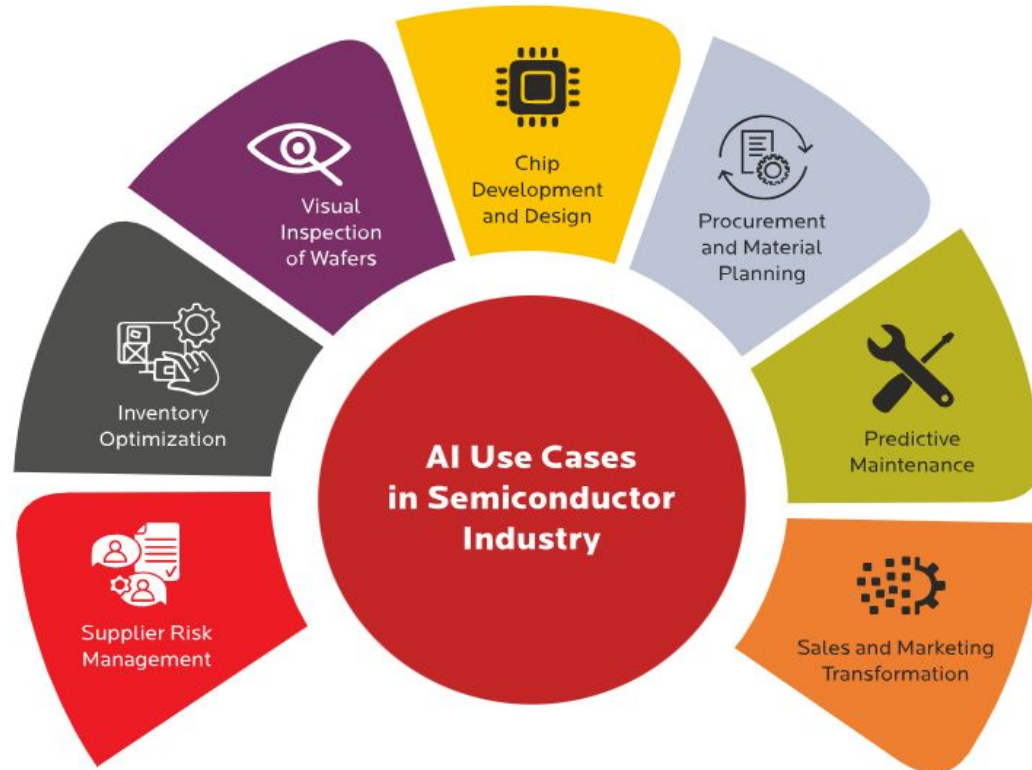
| | Graphic Processing Units | Field Programmable Gate Arrays | Application Specific Integrated Circuits |
|-------------------|--------------------------|--------------------------------|--|
| Power consumption | High | Medium | Low |
| Latency | More | Less | Less |
| Flexibility | Medium | High | Low |
| Efficiency | Low | Medium | High |

AI chips in use

The table given below provides information of the various AI chips in use and their details:

| Type | AI Chip | Use |
|------|-----------------|--|
| GPU | Radeon Instinct | Deep Learning Artificial Neural Network High Performance Computing GPGPU |
| | Tesla V100 | High Performance Computing Data Science Graphics |
| FPGA | Agilex | Data Center 5G Network Smart NICs |
| | Virtex | 10G to 100G Networking Portable Radar |
| ASIC | FSD Computer | Tesla Self Driving Cars |
| | TPU v3 | Custom developed for Google's Machine Learning |

AI in Semiconductor Industrial application



AI Applications in Semiconductor Industry

1.CHIP DEVELOPMENT & DESIGN

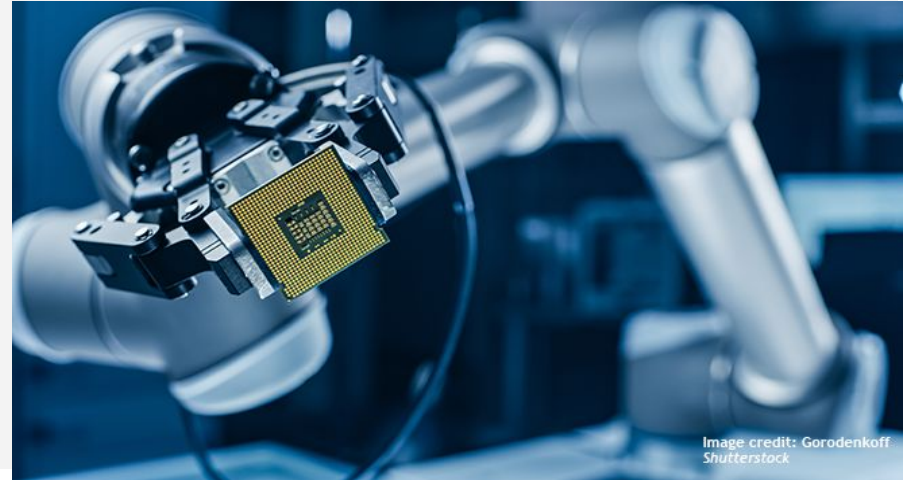
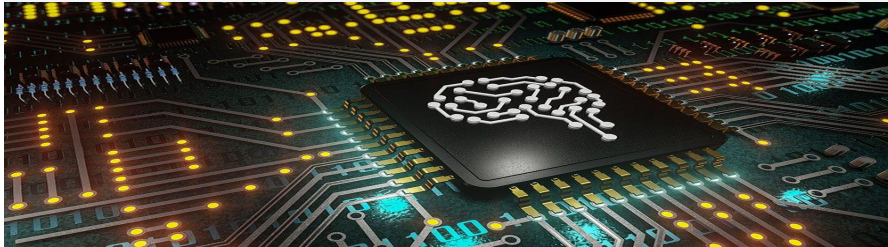
- 1.**ML** algorithms will predict **failure** of designs.
- 2.**Faster** process.

- 3.Improved **design quality**
- 4.30% Production **cost** is **reduced**

2.VIRTUAL INSPECTION OF WAFERS

Thin **Silicon Wafers** Inspected.

AI will accurately **detect** the defects



AI Applications

3.EDGE COMPUTING & IoT:

AI-enabled edge devices and **IoT (Internet of Things)** devices often require specialized processors. The semiconductor industry plays a crucial role in **developing** and **manufacturing** these specialized chips that power AI at the edge.

4.REQUIREMENT PLANNING

1.AI is expert in **Planning & Predictions**

2.With previous data , like market rates of raw materials

How product will **perform** in market

AI Applications

5.LOGISTICS AND SHIPMENT

- 1.**Shipped** to destination on time
- 2.**When** to ship? (for lower cost)
- 3.Track **location** of product

6.SUPPLY CHAIN OPTIMIZATION

AI algorithms can optimize the semiconductor supply chain by predicting demand, managing inventory, and improving logistics. This ensures that the right components are available at the right time and reduces excess inventory costs.

AI-THE FUTURE

AI is revolutionizing the Semiconductor industry by enhancing

1.Efficiency 2.Quality 3.Innovation

in both Manufacturing and Design processes.

Continuously Evolving field.



AI-THE FUTURE

Future Trends Driving the Semiconductor Industry



Artificial Intelligence



Digital supply
networks



Internet of Things
(IoT)

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*Thank
you*

